

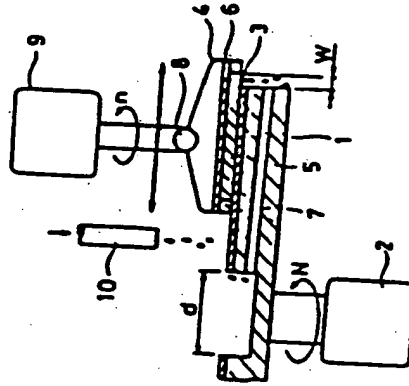
# PATENTS ABSTRACTS OF JAPAN

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(54) METHOD AND APPARATUS FOR WAFER POLISHING  
(11) 1-268032 (A) (43) 25.10.1989 (19) JP  
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**PURPOSE:** To enable accurately polish a wafer into plane form, by polishing the wafer held in a polishing chuck with a part thereof sticking out from a polishing surface plate or a polishing cloth.

**CONSTITUTION:** Each polishing chuck 4 holds one semiconductor wafer 5, which is polished with a part thereof sticking out from a polishing surface plate 1 or a polishing cloth 3. For example, the semiconductor wafer 5 to be polished is held by the polishing chuck 4 by vacuum absorption or any other means, rotating the polishing chuck 4 with a motor 9 forces the semiconductor wafer 5 to rotate together with the polishing chuck 4 at a rotating speed n and presses the wafer 5 on the polishing cloth 3 at a rotating speed n and presses rotated by a motor 2 at a rotating speed N. The semiconductor wafer 5 in this state rotates together with the polishing chuck 4 at a rotating speed n while reciprocating in the direction of the diameter of the polishing surface plate 1 and is polished by the friction between said wafer and the polishing cloth 3, with a part thereof sticking out from the polishing cloth 3 in the inside and outside of the polishing surface plate 1.



## LEGENDE

zu den Bibliographiedaten (54) Titel der Patentanmeldung  
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